

Trench gate field-stop IGBT, HB series 650 V, 40 A high speed

Datasheet - production data

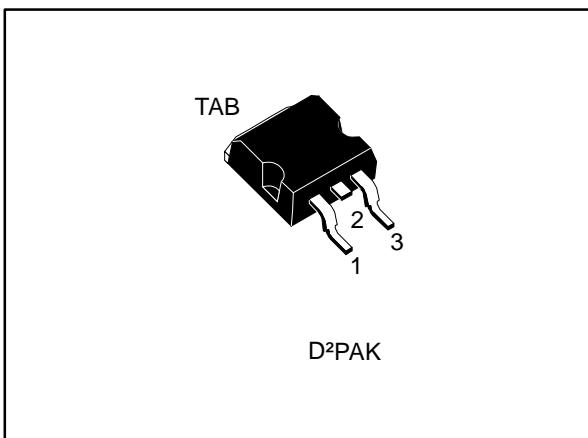
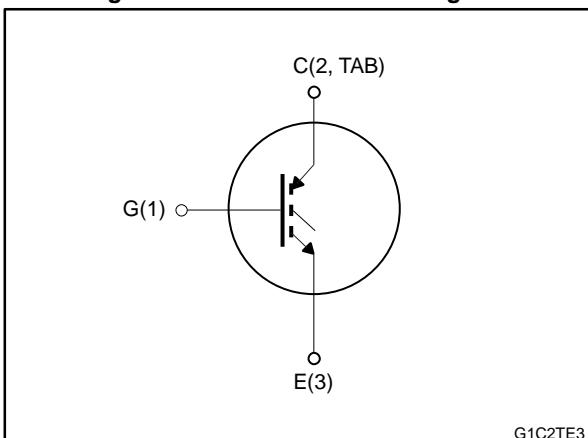


Figure 1: Internal schematic diagram



Features

- Maximum junction temperature: $T_J = 175 \text{ }^{\circ}\text{C}$
- High speed switching series
- Minimized tail current
- Low saturation voltage: $V_{CE(sat)} = 1.6 \text{ V} (\text{typ.})$ @ $I_C = 40 \text{ A}$
- Tight parameter distribution
- Safe paralleling
- Low thermal resistance

Applications

- Photovoltaic inverters
- High frequency converters

Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the new HB series of IGBTs, which represents an optimum compromise between conduction and switching loss to maximize the efficiency of any frequency converter. Furthermore, the slightly positive $V_{CE(sat)}$ temperature coefficient and very tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packing
STGB40H65FB	GB40H65FB	D²PAK	Tape and reel

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$)	650	V
I_C	Continuous collector current at $T_C = 25^\circ\text{C}$	80	A
	Continuous collector current at $T_C = 100^\circ\text{C}$	40	
$I_{CP}^{(1)}$	Pulsed collector current	160	A
V_{GE}	Gate-emitter voltage	± 20	V
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	283	W
T_{STG}	Storage temperature range	- 55 to 150	$^\circ\text{C}$
T_J	Operating junction temperature range	- 55 to 175	

Notes:

(1)Pulse width limited by maximum junction temperature.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case	0.53	$^\circ\text{C}/\text{W}$
R_{thJA}	Thermal resistance junction-ambient	62.5	

2 Electrical characteristics

$T_C = 25^\circ\text{C}$ unless otherwise specified

Table 4: Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0 \text{ V}$, $I_C = 2 \text{ mA}$	650			V
$V_{CE(\text{sat})}$	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}$, $I_C = 40 \text{ A}$		1.6	2	V
		$V_{GE} = 15 \text{ V}$, $I_C = 40 \text{ A}$, $T_J = 125^\circ\text{C}$		1.7		
		$V_{GE} = 15 \text{ V}$, $I_C = 40 \text{ A}$, $T_J = 175^\circ\text{C}$		1.8		
$V_{GE(\text{th})}$	Gate threshold voltage	$V_{CE} = V_{GE}$, $I_C = 1 \text{ mA}$	5	6	7	V
I_{CES}	Collector cut-off current	$V_{GE} = 0 \text{ V}$, $V_{CE} = 650 \text{ V}$			25	μA
I_{GES}	Gate-emitter leakage current	$V_{CE} = 0 \text{ V}$, $V_{GE} = \pm 20 \text{ V}$			± 250	nA

Table 5: Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	$V_{CE} = 25 \text{ V}$, $f = 1 \text{ MHz}$, $V_{GE} = 0 \text{ V}$	-	5412	-	pF
C_{oes}	Output capacitance		-	198	-	
C_{res}	Reverse transfer capacitance		-	107	-	
Q_g	Total gate charge	$V_{CC} = 520 \text{ V}$, $I_C = 40 \text{ A}$, $V_{GE} = 15 \text{ V}$ (see Figure 23: "Gate charge test circuit")	-	210	-	nC
Q_{ge}	Gate-emitter charge		-	39	-	
Q_{gc}	Gate-collector charge		-	82	-	

Table 6: Switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 40 \text{ A}, V_{GE} = 15 \text{ V}, R_G = 5 \Omega$ (see <i>Figure 22: "Test circuit for inductive load switching"</i>)		40	-	ns
t_r	Current rise time			13	-	
$(di/dt)_{on}$	Turn-on current slope			2413	-	A/ μs
$t_{d(off)}$	Turn-off-delay time			142	-	ns
t_f	Current fall time			27	-	
$E_{on}^{(1)}$	Turn-on switching energy			498	-	μJ
$E_{off}^{(2)}$	Turn-off switching energy			363	-	
E_{ts}	Total switching energy			861	-	
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400 \text{ V}, I_C = 40 \text{ A}, V_{GE} = 15 \text{ V}, R_G = 5 \Omega$ $T_J = 175^\circ\text{C}$ (see <i>Figure 22: "Test circuit for inductive load switching"</i>)		38	-	ns
t_r	Current rise time			14	-	
$(di/dt)_{on}$	Turn-on current slope			2186	-	A/ μs
$t_{d(off)}$	Turn-off-delay time			141	-	ns
t_f	Current fall time			61	-	
$E_{on}^{(1)}$	Turn-on switching energy			1417	-	μJ
$E_{off}^{(2)}$	Turn-off switching energy			764	-	
E_{ts}	Total switching energy			2181	-	

Notes:

⁽¹⁾Energy losses include reverse recovery of the external diode. The diode is the same of the co-packed STGW40H65DFB.

⁽²⁾Including the tail of the collector current.

2.1

Electrical characteristics (curves)

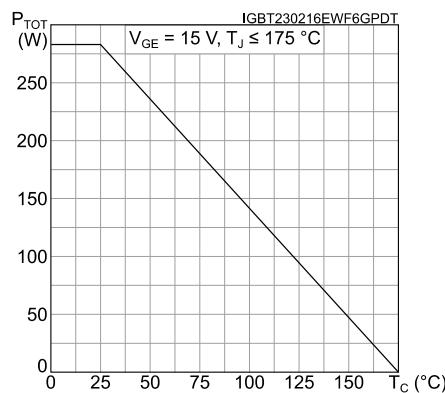
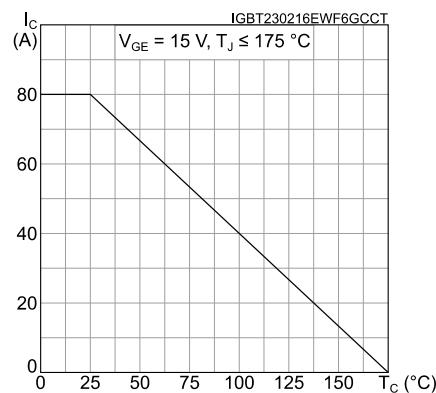
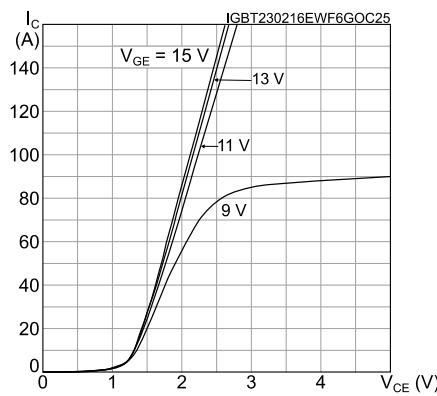
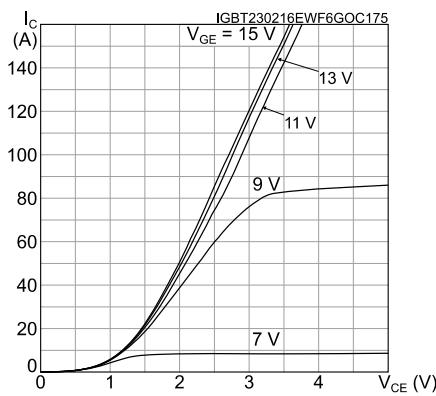
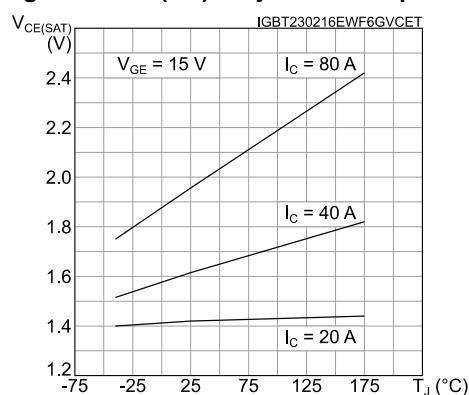
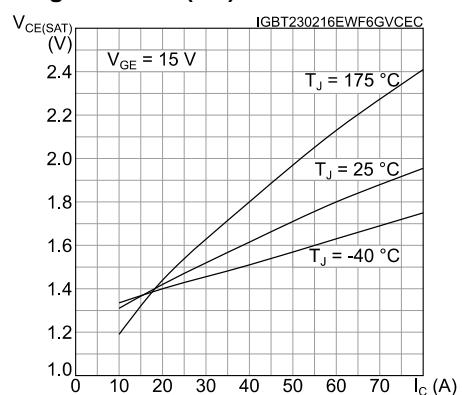
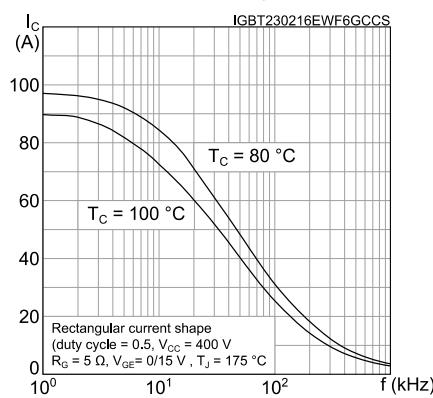
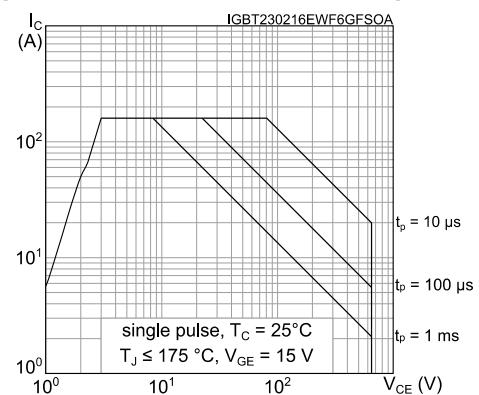
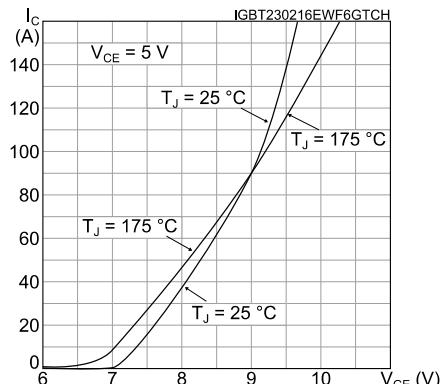
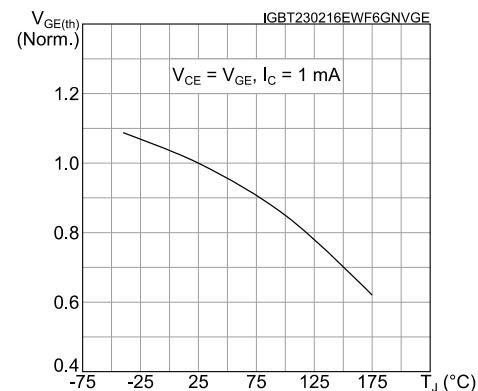
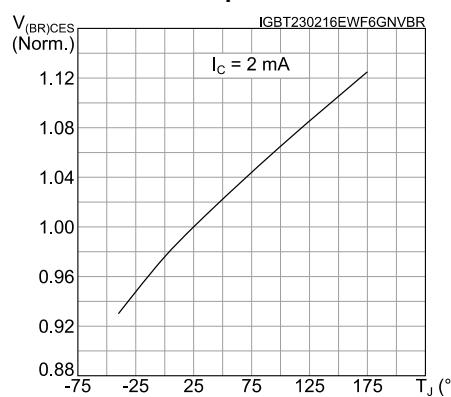
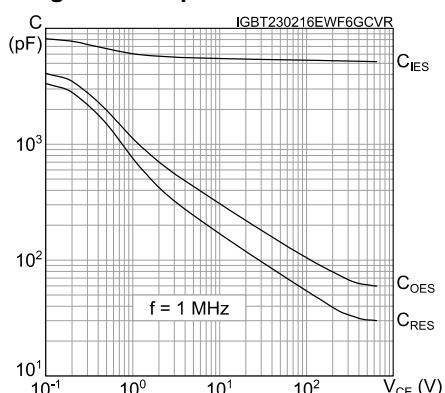
Figure 2: Power dissipation vs. case temperature**Figure 3: Collector current vs. case temperature****Figure 4: Output characteristics ($T_J = 25$ °C)****Figure 5: Output characteristics ($T_J = 175$ °C)****Figure 6: $V_{CE(sat)}$ vs. junction temperature****Figure 7: $V_{CE(sat)}$ vs. collector current**

Figure 8: Collector current vs. switching frequency**Figure 9: Forward bias safe operating area****Figure 10: Transfer characteristics****Figure 11: Normalized VGE(th) vs. junction temperature****Figure 12: Normalized V(BR)CES vs. junction temperature****Figure 13: Capacitance variations**

Electrical characteristics

STGB40H65FB

Figure 14: Gate charge vs. gate-emitter voltage

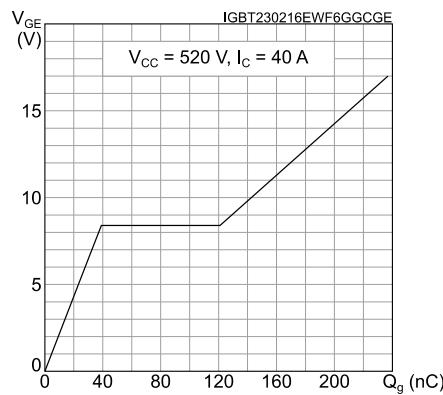


Figure 15: Switching energy vs. collector current

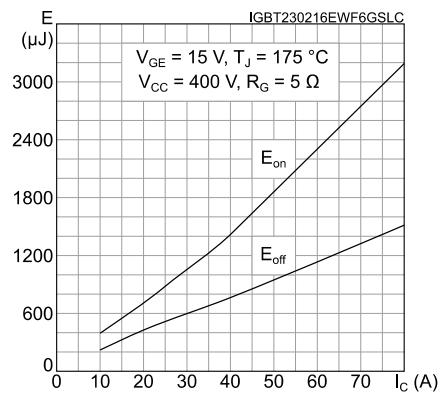


Figure 16: Switching energy vs. gate resistance

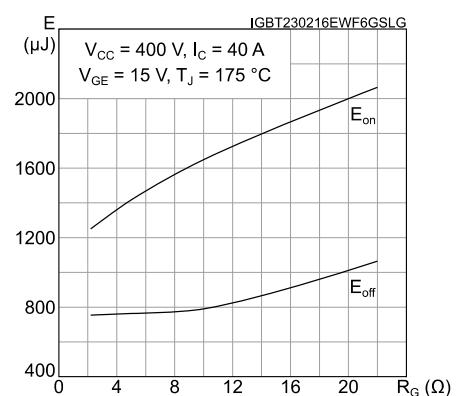


Figure 17: Switching energy vs. temperature

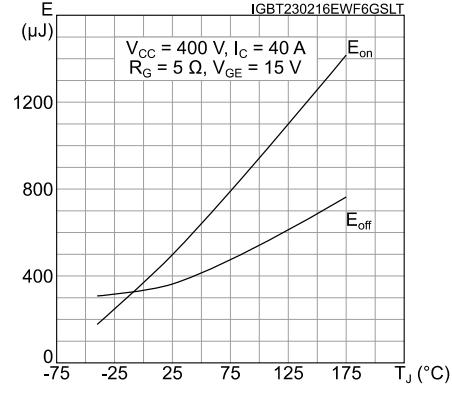


Figure 18: Switching energy vs. collector emitter voltage

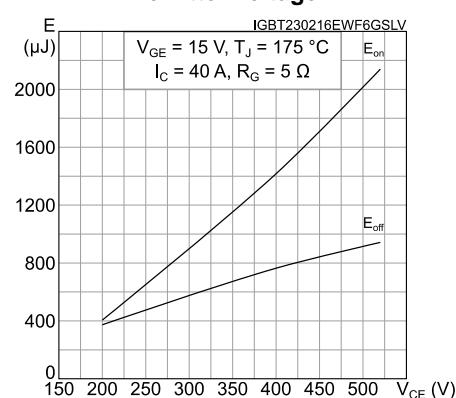


Figure 19: Switching times vs. collector current

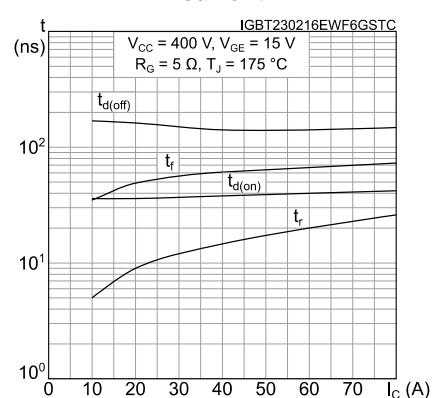
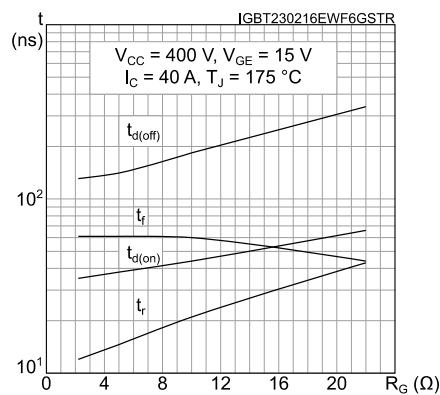
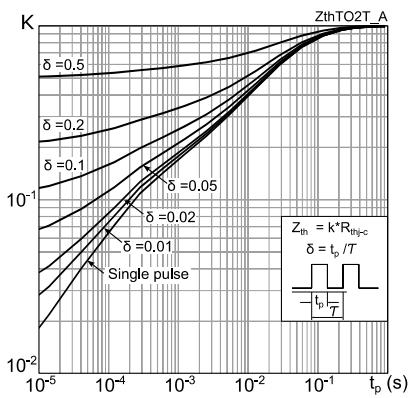
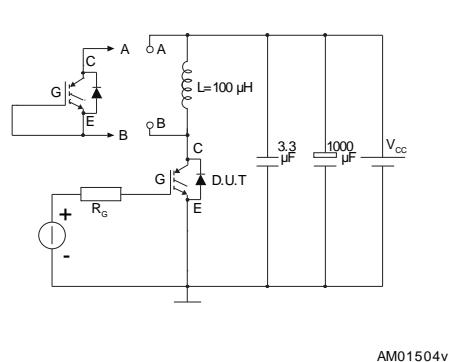


Figure 20: Switching times vs. gate resistance**Figure 21: Thermal impedance**

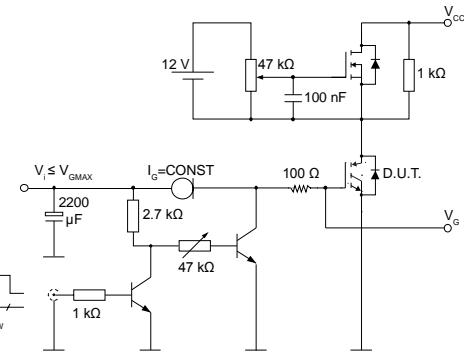
3 Test circuits

Figure 22: Test circuit for inductive load switching



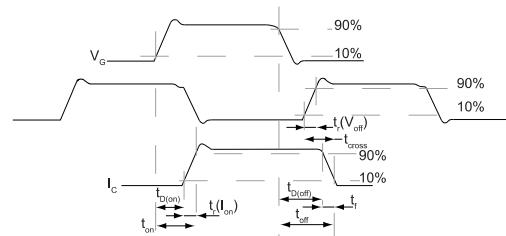
AM01504v1

Figure 23: Gate charge test circuit



AM01505v1

Figure 24: Switching waveform



AM01506v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
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4.1 D²PAK package information

Figure 25: D²PAK (TO-263) type A package outline

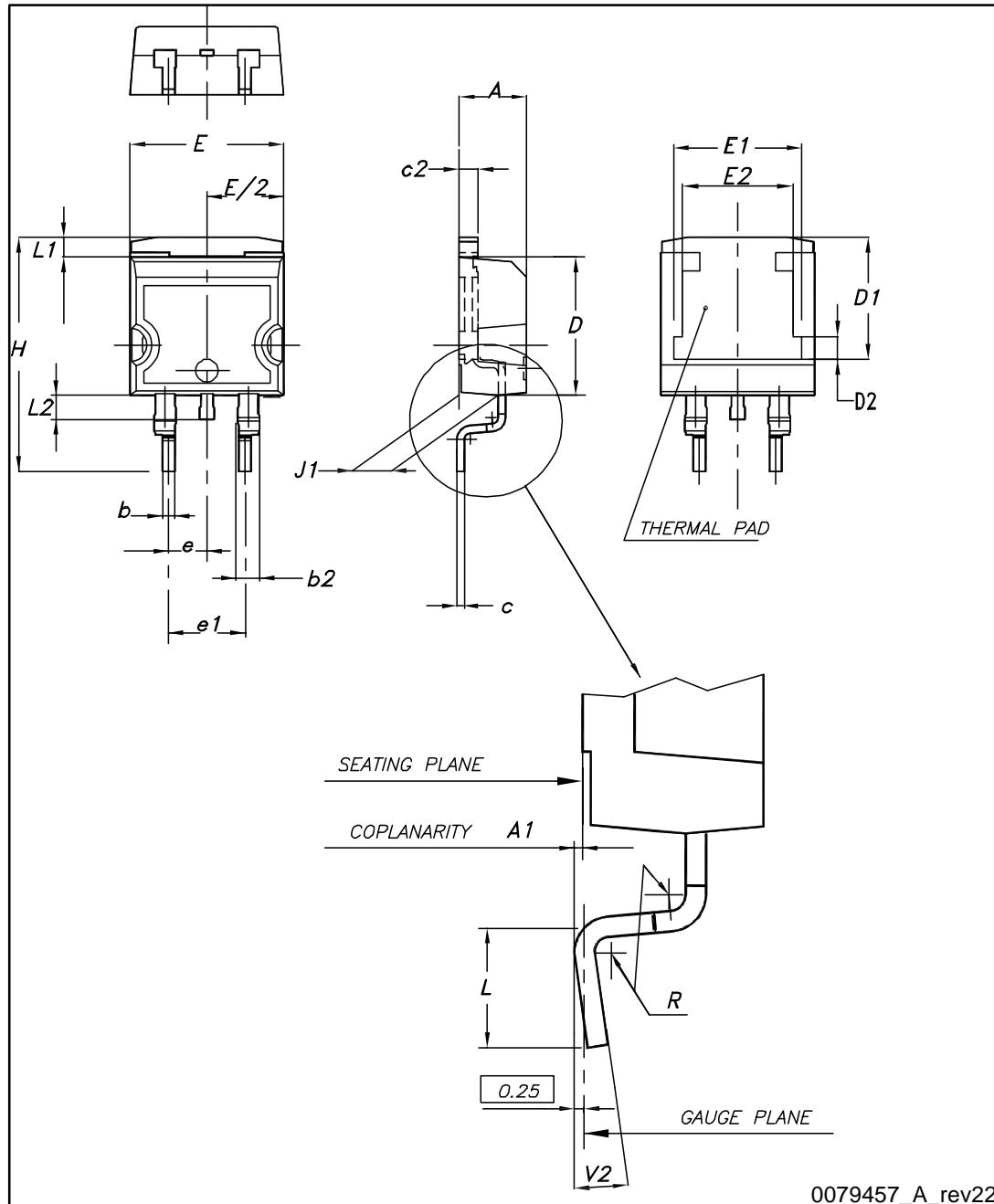
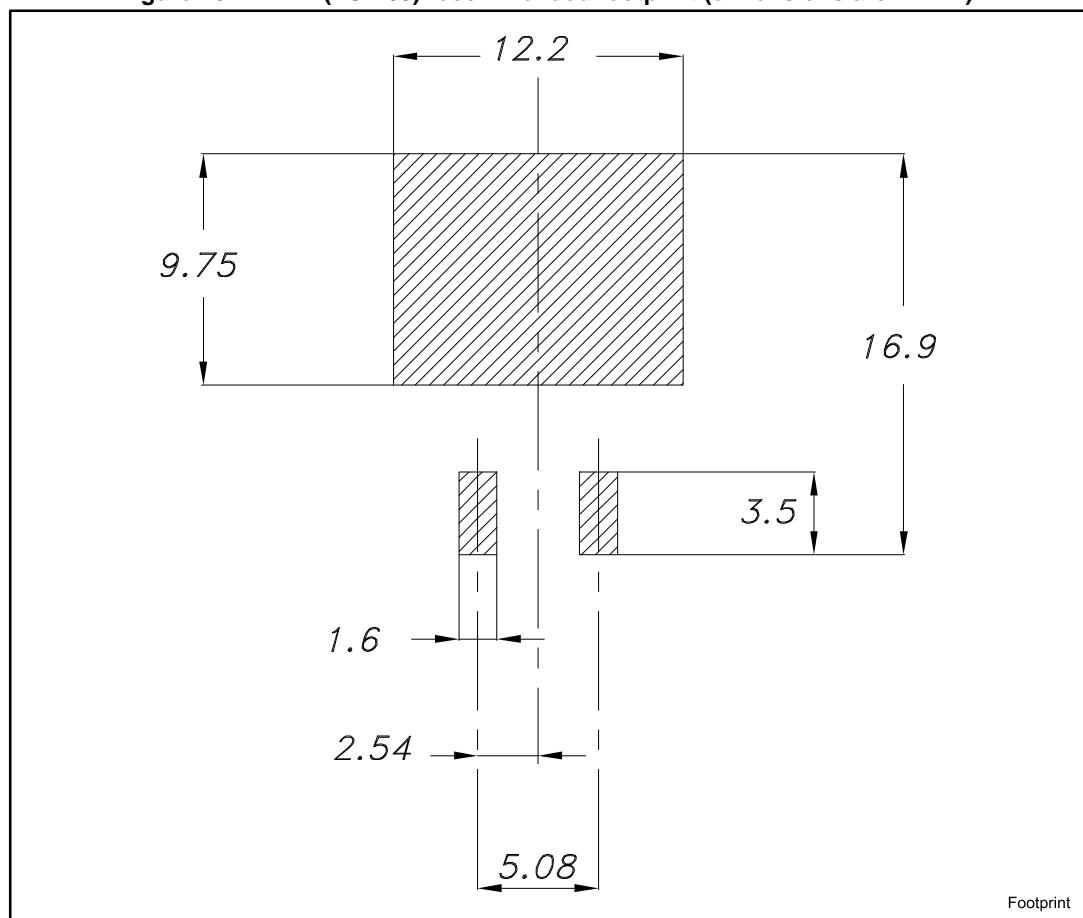


Table 7: D²PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 26: D²PAK (TO-263) recommended footprint (dimensions are in mm)

4.2 D²PAK packing information

Figure 27: Tape outline

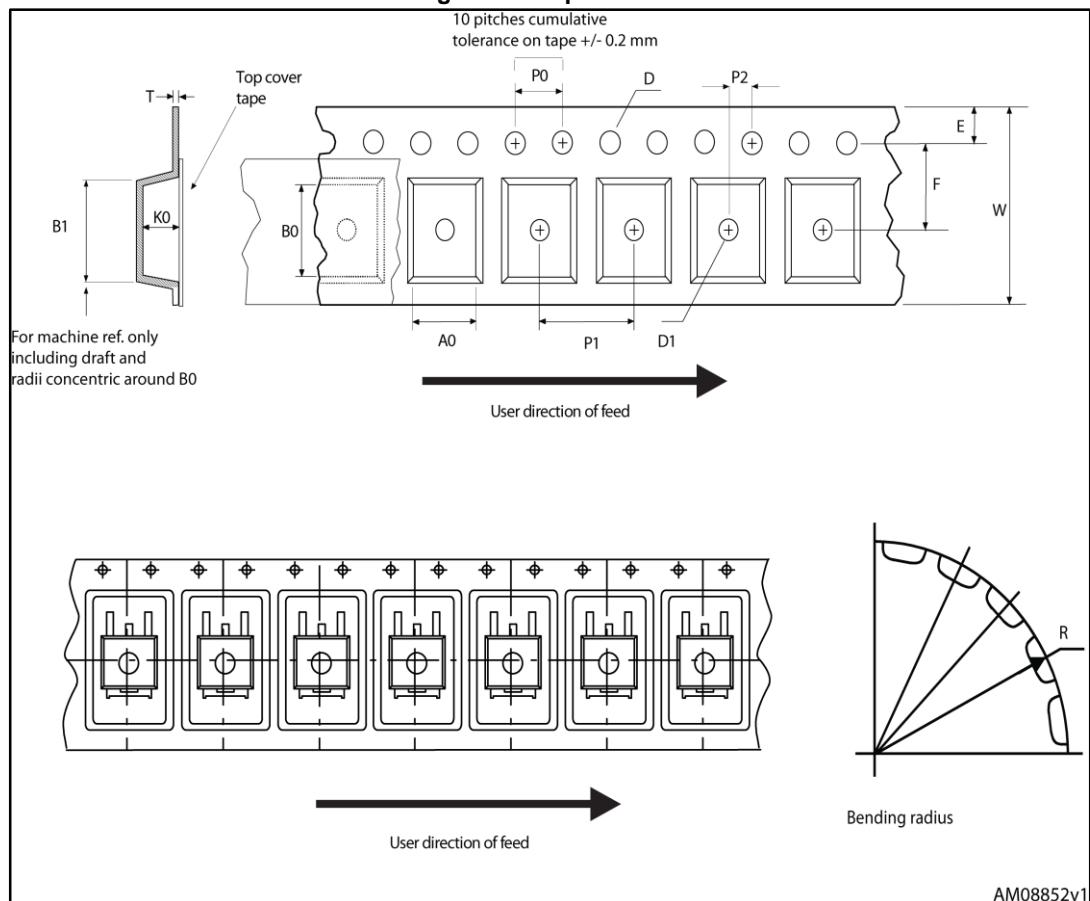
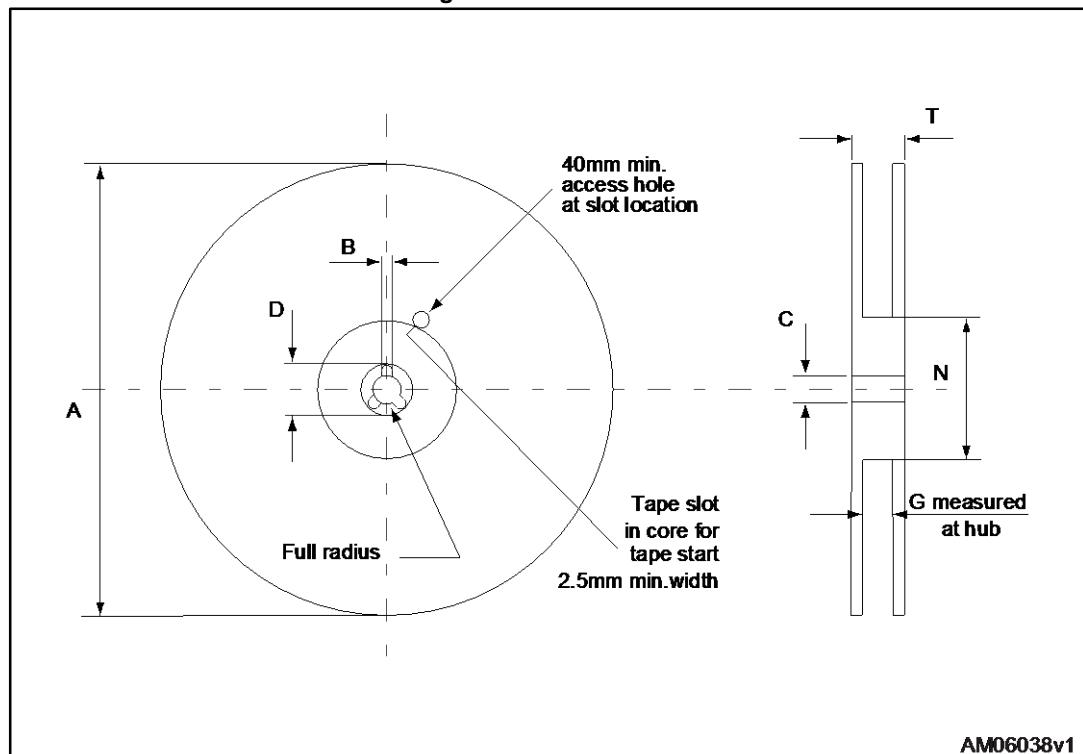


Figure 28: Reel outline

Table 8: D²PAK tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

5 Revision history

Table 9: Document revision history

Date	Revision	Changes
27-Jun-2016	1	Initial release.

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